

## Product / Process Change Notice

**Parts Affected:**

All discrete semiconductor devices manufactured in the SOT-89 package.

**Extent of Change:**

Copper wire has been added as a qualified material for wire bonding in addition to the currently used gold wire.

**Reason for Change:**

This change will insure an uninterrupted flow of product and provide increased flexibility for supply chain management.

**Effect of Change:**

This change does not affect the form, fit, or function of any device. Devices assembled with gold wire will continue to be manufactured concurrently with devices assembled with copper wire.

**Qualification:**

Standard evaluation and qualifications completed resulting in no performance differences compared to current product.

**Effective Date of Change:**

February 1, 2012.

**Sample Availability:**

Please contact Salesperson or Manufacturer's Representative.